

Filename: PMP8764_REVB_bom.xls

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PMP8764_REVB BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	3.3uF	CAP ALUM 3.3UF 400V 20% RADIAL	0.315 inch	400LLE3R3MEFC8X11R5	Rubycon
1	C100	47pF	Capacitor, Ceramic, 50V, C0G, 5%	0402	STD	STD
1	C101	220pF	CAP CER 220PF 250VAC X1Y2 RAD	7.00 Dia mm	STD	STD
1	C2	0.022uF	Capacitor, Ceramic, 630V, X7R, 15%	1206	STD	STD
1	C3	22uF	Capacitor, Ceramic, 25V, X5R, 15%	1206	STD	STD
1	C4	100uF	CAP ALUM 100UF 16V 20% RADIAL	0.248 inch	16ZLH100MEFC5X11	Rubycon
1	C6	1uF	Capacitor, Ceramic, 50V, X7R, 15%	0805	STD	STD
1	D1	SMAJ120A	Diode, Transient Voltage Suppressor, 120V	SMA	SMAJ120A	Bourns
1	D2	RH06-T	Diode, Bridge, 0.5-A, 600-V	MiniDIP	RH06-T	Diodes
1	D3	MRA4007	Diode, Rectifier, 1A, 1000V, SMA	SMA	STD	STD
1	D4	ES1B	DIODE FAST 1A 100V SMA	0.220 x 0.115 inch	ES1B	STD
1	D5	1N4148	Diode, Signal, 300-mA, 75-V, 350-mW	SOD-123	1N4148W-7-F	Diodes
1	F1	0.5A	FUSE SLOW 250VAC 500MA RADIAL	4x8.35 mm	RST500	BEL Fuse
1	Q1	AOU1N60	MOSFET N-CH 600V 1.3A TO251	TO-220V	AOU1N60	Alpha Omega
2	R1, R3	10MEG	Resistor, 1/4 watt, 5%	1206	STD	STD
1	R100	10k	Resistor, Chip, 1/16W, 5%	0603	STD	STD
1	R2	510	Resistor, 1/4 watt, 5%	1206	STD	STD
1	R4	20	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R5	100k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R6	28.0k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R7	1.50k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R8	3.9	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R9	DNP	Do Not Populate	0402	N/A	N/A
1	T2	3 mH	Transformer, ±10%	17.9x20.3 mm	750313651	
2	TP1, TP4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	TP2	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone
1	TP3	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	UCC28700DBV	IC, Constant Voltage, Constant Current PWM With Primary Side Regulation		UCC28700DBV	

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